

APBL3025EYC-F01

3.0 x 2.5 mm Surface Mount LED Lamp



DESCRIPTIONS

- The High Efficiency Red source color devices are Made with Gallium Arsenide Phosphide on Gallium Phosphide Orange Light Emitting Diode
- The Yellow source color devices are made with Gallium Arsenide Phosphide on Gallium Phosphide Yellow Light Emitting Diode

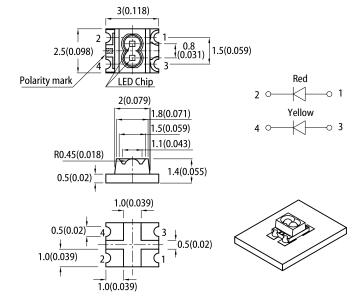
FEATURES

- 3.0 mm x 2.5 mm SMD LED, 1.4 mm thickness
- Low power consumption
- · Wide viewing angle
- · Ideal for backlight and indicator
- · Inner lens type
- Moisture sensitivity level: 3
- Package: 2000 pcs / reel
- Halogen-free
- RoHS compliant

APPLICATIONS

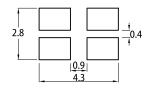
- Backlight
- · Status indicator
- · Home and smart appliances
- · Wearable and portable devices
- · Healthcare applications

PACKAGE DIMENSIONS



RECOMMENDED SOLDERING PATTERN

(units: mm; tolerance: \pm 0.1)



- Notes:
 1. All dimensions are in millimeters (inches).
 2. Tolerance is ±0.2(0.008") unless otherwise noted.
- The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.

 The device has a single mounting surface. The device must be mounted according to the specifications.

SELECTION GUIDE

Part Number	Emitting Color (Material)	Lens Type	Iv (mcd) @ 20mA [2]		Viewing Angle [1]
			Min.	Тур.	201/2
APBL3025EYC-F01	High Efficiency Red (GaAsP/GaP)	- Water Clear	12	20	70°
			*8	*15	
	Yellow (GaAsP/GaP)		5	15	
			*5	*15	

INDICES.

1. 61/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.

2. Luminous intensity / luminous flux: +/-15%.

* Luminous intensity value is traceable to CIE127-2007 standards.





ELECTRICAL / OPTICAL CHARACTERISTICS at T_A=25°C

Parameter	Symbol	Emitting Color	Value		Unit
raiailietei			Тур.	Max.	Oillt
Wavelength at Peak Emission I _F = 20mA	λ_{peak}	High Efficiency Red Yellow	627 590	-	nm
Dominant Wavelength I _F = 20mA	λ _{dom} ^[1]	High Efficiency Red Yellow	617 588	-	nm
Spectral Bandwidth at 50% Φ REL MAX $I_F = 20$ mA	Δλ	High Efficiency Red Yellow	45 35	-	nm
Capacitance	С	High Efficiency Red Yellow	15 20	-	pF
Forward Voltage I _F = 20mA	V _F ^[2]	High Efficiency Red Yellow	2 2.1	2.5 2.5	V
Reverse Current (V _R = 5V)	I _R	High Efficiency Red Yellow	-	10 10	μА

ABSOLUTE MAXIMUM RATINGS at T_A=25°C

Danamatan	Symbol	Va	11-24	
Parameter		High Efficiency Red	Yellow	Unit
Power Dissipation	P _D	75	75	mW
Reverse Voltage	V _R	5	5	V
Junction Temperature	T _J	125	110	°C
Operating Temperature T _{op} -40 To +85		o +85	°C	
Storage Temperature	T _{stg}	-40 To +85		°C
DC Forward Current	I _F	30	30	mA
Peak Forward Current	_{FP} ^[1]	160	140	mA
Electrostatic Discharge Threshold (HBM)	-	8000	8000	V

Notes:
1. 1/10 Duty Cycle, 0.1ms Pulse Width.
2. Relative humidity levels maintained between 40% and 60% in production area are recommended to avoid the build-up of static electricity – Ref JEDEC/JESD625-A and JEDEC/J-STD-033.



Notes:

1. The dominant wavelength (λd) above is the setup value of the sorting machine. (Tolerance λd:±1nm.)

2. Forward voltage: ±0.1V.

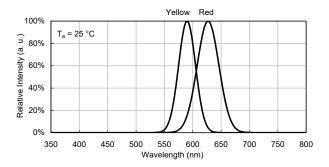
3. Wavelength value is traceable to CIE127-2007 standards.

4. Excess driving current and / or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

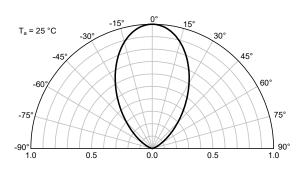


TECHNICAL DATA

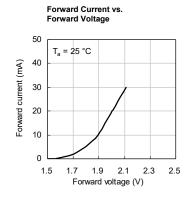
RELATIVE INTENSITY vs. WAVELENGTH

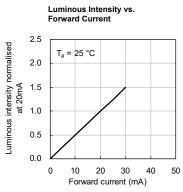


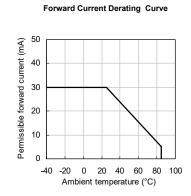
SPATIAL DISTRIBUTION

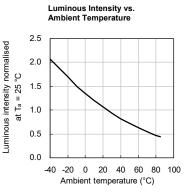


HIGH EFFICIENCY RED

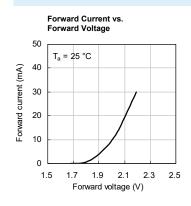


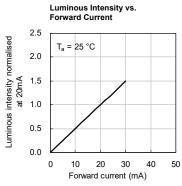


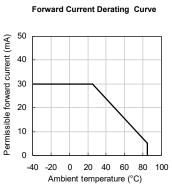


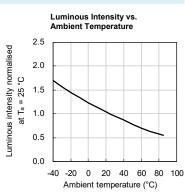


YELLOW







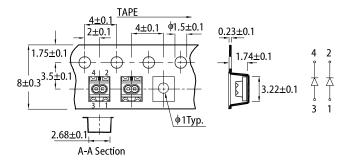




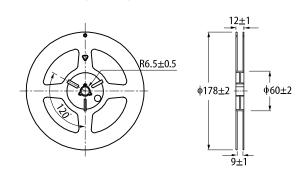
REFLOW SOLDERING PROFILE for LEAD-FREE SMD PROCESS

300 above 255°C (°C) 260°C max. 30s max. 10s max. 250 3°C/s max. 6°C/s max. 200 150 Temperature pre-heating 100 150~200°C above 217°C 60~120s 60~150s 50 25°C 0 50 100 150 200 250 0 300 (sec) Time

TAPE SPECIFICATIONS (units:mm)

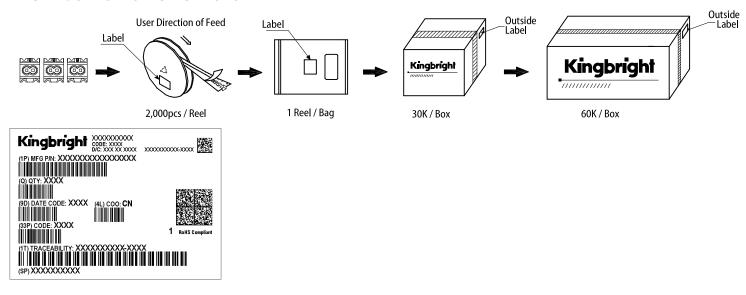


REEL DIMENSION (units: mm)



- 1. Don't cause stress to the LEDs while it is exposed to high temperature.
 2. The maximum number of reflow soldering passes is 2 times.
 3. Reflow soldering is recommended. Other soldering methods are not recommended as they might cause damage to the product.

PACKING & LABEL SPECIFICATIONS



PRECAUTIONARY NOTES

- The information included in this document reflects representative usage scenarios and is intended for technical reference only.
- The part number, type, and specifications mentioned in this document are subject to future change and improvement without notice. Before production usage customer should refer
- to the latest datasheet for the updated specifications.

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